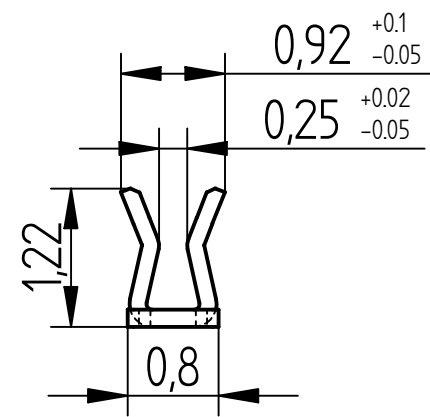
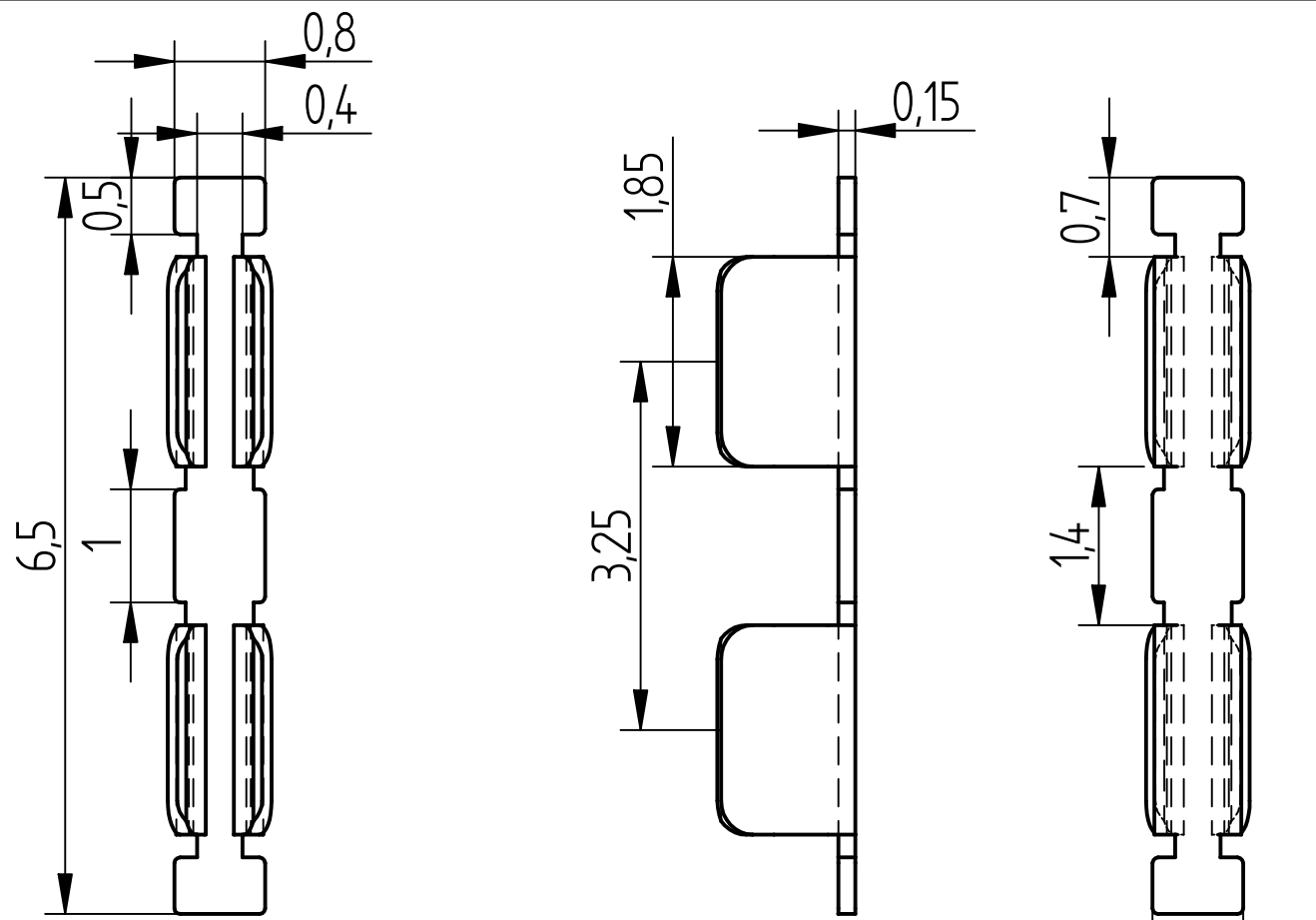
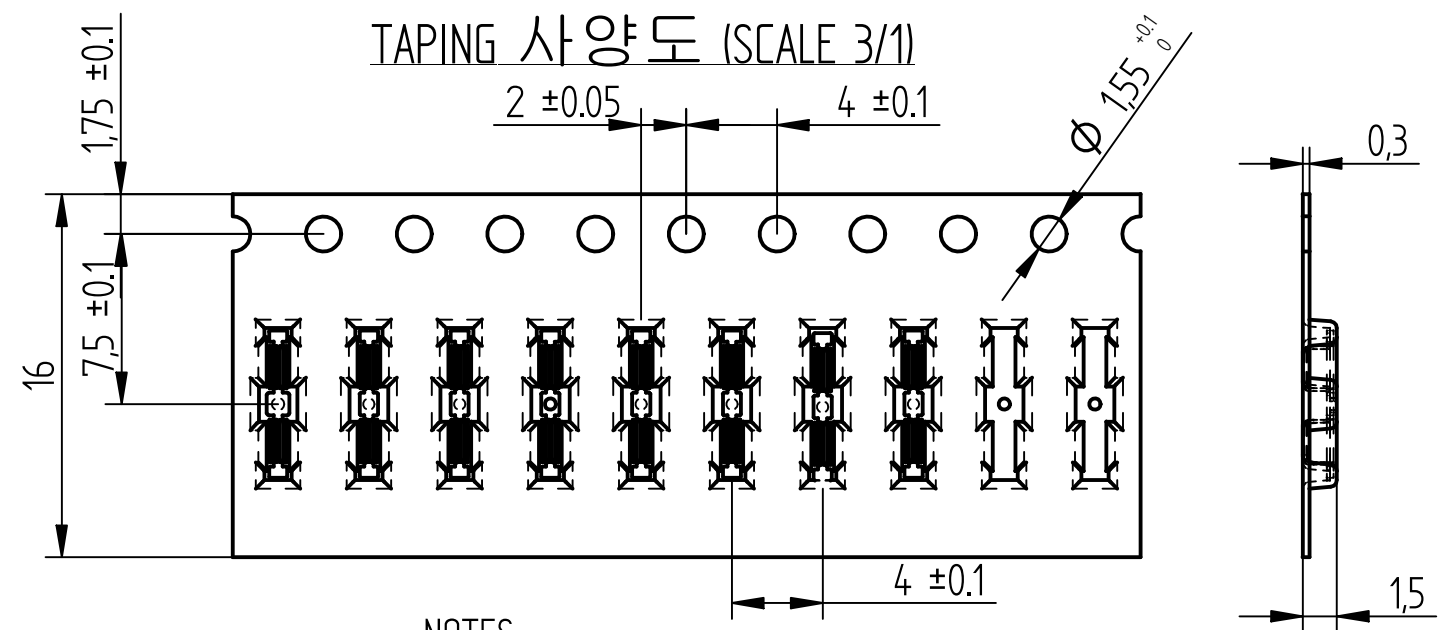


REVISION HISTORY			
REV	DESCRIPTION	DATE	APPROVED
A	신규 제정	2011.05.23	P.K.KOH
B	인이부 치수 변경 0.8 ⇒ 0.92mm	2011.06.09	P.K.KOH
C	SHIELD CASE THICKNESS 0.3±0.02 ⇒ 0.3 + 0.02 -0	2012.03.30	P.K.KOH



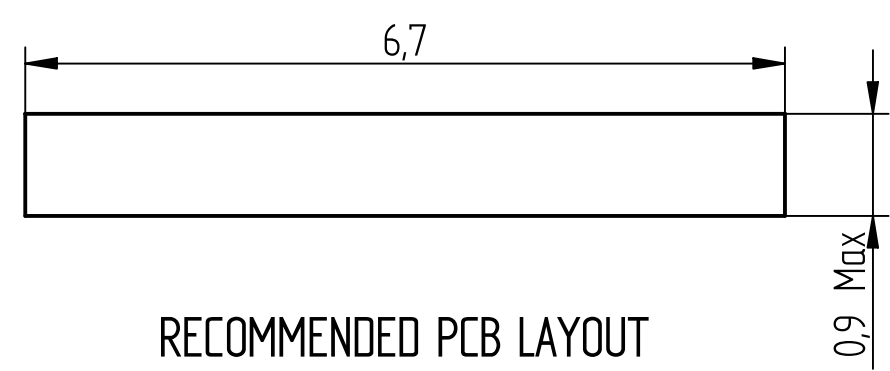
SCALE : 15/1

TAPING 사양도 (SCALE 3/1)

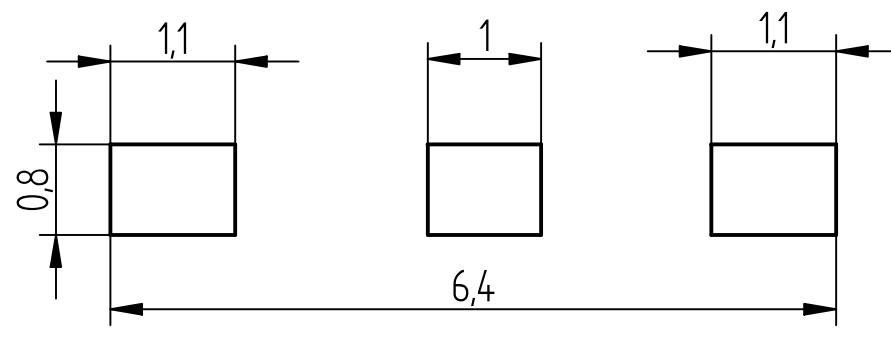


NOTES

1. MATERIAL : SUS301
2. MATERIAL THICKNESS : 0.15±
3. FINISHED : Sn(100%) PLATING ON BOTH SIDE
(NI 0.5 μ m Sn 1.27 μ m)
4. PACKING MATERIALS.
- REEL : HIPS 0.3±
- COVER TAPE : PS
- Q'TY/REEL : 10,000ea
5. AVAILABLE SHIELD CASE THICKNESS : 0.3+ 0.02 -0
6. CONTACT RESISTANCE 300m Ω MAX
7. STENCIL THICKNESS : 0.12T
8. Maintain 90°±3 while engage & disengage shield can & shield clip to prevent deformation & to maintain retention force of shield clip



RECOMMENDED PCB LAYOUT



RECOMMENDED STENCIL LAY-OUT 0.1T

DATA	NAME	INNOCHIPS TECHNOLOGY ICT (주)이노칩테크놀로지	
APP. 2011.05.23	LEE	TITLE SHILED CLIP	
CHECK		SIZE A3	DWG NO ICSRC6508-025SFR
DESIG. 2011.05.23	P.K.KOH	FILE NAME: ICSRC6508-025SFR.dft	REV C
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE ANGLES ± 0.3° 0~1 ± 0.05 1~5 ± 0.1 5 ~ 10 ± 0.15		SCALE:	WEIGHT: SHEET 1 OF 1